




<b>PCN Number:</b>		20190509001.1		<b>PCN Date:</b>		May 13, 2019																			
<b>Title:</b>		Transfer of select DLM devices from GFAB to FFAB Wafer Fab site																							
<b>Customer Contact:</b>		<a href="#">PCN Manager</a>		<b>Dept:</b>		Quality Services																			
<b>Proposed 1<sup>st</sup> Ship Date:</b>		Aug 13, 2019		<b>Estimated Sample Availability:</b>		Date provided at sample request.																			
<b>Change Type:</b>																									
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																				
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																				
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																				
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																				
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																				
		<input type="checkbox"/>	Part number change																						
<b>PCN Details</b>																									
<b>Description of Change:</b>																									
This change notification is to announce the transfer of select DLM devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.																									
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">New Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>New Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>GFAB6</td> <td>DLM</td> <td>150 mm</td> <td>FFAB</td> <td>DLM</td> <td>200 mm</td> </tr> </tbody> </table>								Current Fab Site			New Fab Site			Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter	GFAB6	DLM	150 mm	FFAB	DLM	200 mm
Current Fab Site			New Fab Site																						
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter																				
GFAB6	DLM	150 mm	FFAB	DLM	200 mm																				
Qual details are provided in the Qual Data Section.																									
<b>Reason for Change:</b>																									
Greenock, Scotland (GFAB) Wafer Fab site closure																									
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																									
None																									
<b>Changes to product identification resulting from this PCN:</b>																									
<b>Current</b>																									
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																						
GFAB6	GF6	GBR	Greenock																						
<b>New Fab Site</b>																									
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																						
<b>FR-BIP-1</b>	<b>TID</b>	<b>DEU</b>	<b>Freising</b>																						
Sample product shipping label (not actual product label)																									
 MADE IN: Malaysia 2DC: 2G:				(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS																					
MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 <b>LBL: 5A (L) TO: 1750</b>																									
<b>Product Affected Group:</b>																									
DS36277TMX/NOPB	DS8921ATM/NOPB	LM317LITPX/NOPB	LM9071S/NOPB																						
DS3695AM/NOPB	DS8921M/NOPB	LM614 MDC	LM9071SX/NOPB																						
DS3695AMX/NOPB	DS8921MX/NOPB	LM9061M/NOPB	LM9071SX/S5000467																						
DS8921AM/NOPB	LM317LITP/NOPB	LM9061MX/NOPB	LMB1024MX-1/E7001820																						
DS8921AMX/NOPB																									

## Qualification Report

Approve Date 7-May-2019

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM9061QDRQ1	QBS Reference: LM2576HVT-5.0/NOPB
HAST	Bias ed HAST, 130C/85%RH	96 Hours	3/231/0	-
AC	Autoclave 121C	96 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	2/1600/0	3/2400/0
HBM	ESD - HBM	2500 V	3/9/0	-
CDM	ESD - CDM	1500 V	3/9/0	-
LU	Latch-up	(per JESD78)	3/18/0	-
ED	Electrical Distributions	Per Datasheet Parameters	3/90/0	-

- Qual Device LM9061QDRQ1 is qualified at LEVEL3-260C

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Bias ed HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>